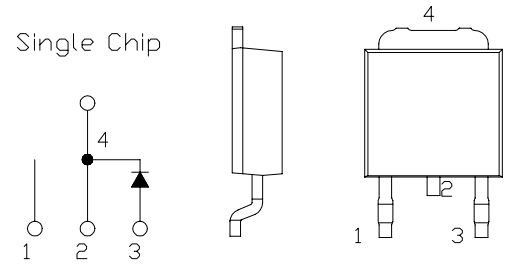


FRD Type : EA31FS2-F

OUTLINE DRAWING

FEATURES

- * TO-252AA Case, Surface Mounting Device
- * Packaged in 16mm Tape and Reel
- * Ultra – Fast Recovery
- * Low Forward Voltage drop
- * Low Power Loss
- * High Surge Capability
- * 200 Volts thru 600 Volts Types Available



Maximum Ratings

Approx Net Weight:0.30g

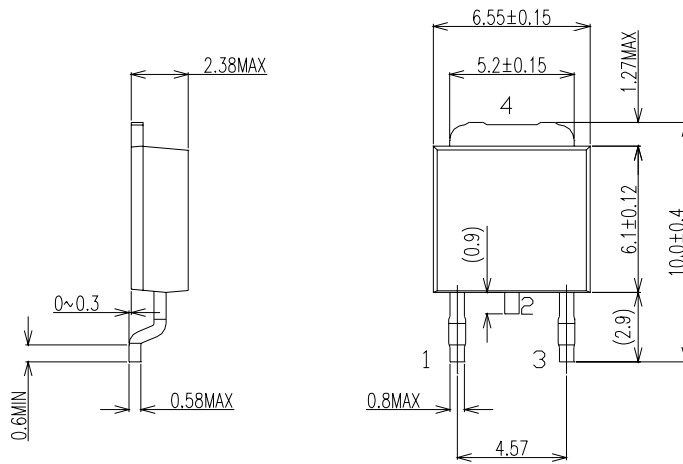
Rating		Symbol	EA31FS2-F			Unit
Repetitive Peak Reverse Voltage		V _{RRM}	200			V
Non-repetitiv Peak Reverse Voltage		V _{RSM}	220			
Average Rectified Output Current	P.C.Board mounted *	I _O	1.7	Ta=30℃	50Hz Half Sine Wave Resistive Load	A
	-		3.0	Tc=129℃		
RMS Forward Current		I _{F(RMS)}	4.71			A
Surge Forward Current		I _{FSM}	45	50Hz Half Sine Wave,1cycle, Non-repetitive		A
Operating JunctionTemperature Range		T _{jw}	- 40 to + 150			℃
Storage Temperature Range		T _{stg}	- 40 to + 150			℃

Electrical • Thermal Characteristics

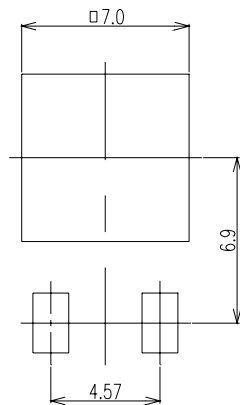
Characteristics		Symbol	Conditions	Min	Typ	Max	Unit
Peak Reverse Current		I_{RM}	$T_j=25^{\circ}C, V_{RM}=V_{RRM}$ per Arm	-	-	10	μA
Peak Forward Voltage		V_{FM}	$T_j=25^{\circ}C, I_{FM}= 3 A$ per Arm	-	-	0.98	V
Reverse Recovery Time		t_{rr}	$I_{FM}= 3 A$, $-di/dt= 50 A/\mu s$, $T_a= 25^{\circ}C$	-	-	30	ns
Thermal Resistance	Junction to Ambient	$R_{th(j-a)}$	P.C.Board mounted *	-	-	80	$^{\circ}C/W$
	Junction to Case	$R_{th(j-c)}$	-	-	-	6	$^{\circ}C/W$

* Print Land = 20x20 mm

EA31FS2-F OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD



Single Chip

